



The 9th International Congress on Laser Advanced Materials Processing

Venue: Sinfonia Technology Hibiki Hall Ise, Ise-city, Mie, Japan

Date: June 10-13, 2025

<http://www.jlps.gr.jp/lamp/lamp2025/>

Sponsorship Opportunities

Welcome to join us at LAMP2025!

The International Congress on Laser Advanced Materials Processing (LAMP) deals with the science and technology of advanced laser materials processing, covering precision microfabrication and high power laser processing. LAMP2025 will be held from JUNE 10-13, 2025 in Ise-city, Mie-prefecture, Japan. LAMP2025 consists of two international symposia: Laser Precision Microfabrication (LPM) and High Power Laser Processing (HPL). It covers hardware and software for fundamental research and industrial applications in both micro and macro processing. LAMP2025 is planned as a four-day event featuring a Plenary Session, Oral and Poster Sessions, LPM Special Sessions focusing on topical issues, and an exhibition hosting prominent figures in this field worldwide. The aim of this congress is to provide a forum for discussing fundamental aspects of laser-matter interaction, the state-of-the-art in laser materials processing, and next-generation topics with fundamental scientists, end-users and laser manufacturers.

We would like to encourage you to become a LAMP2025 sponsor. Please select your sponsorship category: Gold, Silver, Bronze Level Sponsorships and Catalog Display. For the details, please refer to the following pages. Also, if you are interested in Table-top Exhibition, please refer to the other application form. Thank you for your attention in advance.

Dr. Yasuhiro Okamoto, General Chair, LAMP2025

Contact:

LAMP2025 Secretariat, Japan Laser Processing Society
c/o Joining and Welding Research Institute, Osaka University,
11-1 Mihogaoka, Ibaraki, Osaka 567-0047, Japan
TEL/FAX: +81-6-6879-8642, E-mail: lamp2025@jlps.gr.jp

CATEGORY	GOLD LEVEL	SILVER LEVEL	BRONZE LEVEL	CATALOG Display
FEE (10% Tax included)	JPY 200000-	JPY 100000-	JPY 50000-	JPY 30000-
COMPANY MOVIE	YES	YES	YES	
ADVERTISEMENT	2 pages	1 page		
REGISTRATION	To be waived for one person (Banquet:Excluded)	To be waived for one person (Banquet: Excluded)		
CATALOG DISPLAY				Up to 200 sheets

1) Company Logo (For all sponsors)

The company name and logo will be shown on the congress website and in the venue.
Please send JPG file at lamp2025@jlps.gr.jp

2) Movie (For GOLD, SILVER and BRONZE level sponsors)

Company movie URL (YouTube, etc.) will be linked on the congress website.

3) Advertisement (For GOLD and SILVER level sponsors)

A4 sized advertisement(s) will be listed on the congress website.
Size: A4, Margin: 10 mm each., Language: English (Suggested)
Please send PDF (with embedded fonts) at lamp2025@jlps.gr.jp

4) Catalog (Only for Catalog Display sponsors)

200 hardcopies of catalog will be displayed in the venue as "Take Free" materials.
The catalog should be sent to the Secretariat by April 30.

Sending address

LAMP2025 Secretariat, Japan Laser Processing Society
c/o Joining and Welding Research Institute, Osaka University,
11-1 Mihogaoka, Ibaraki, Osaka 567-0047, Japan, TEL: +81-6-6879-8642

5) After the event: Congress Report (For all sponsors)

Event Report will be sent to all sponsors after the event.
Please note that "Participants List" will not include any personal information.

SPONSORSHIP APPLICATION DUE DATE: APRIL 10, 2025

Please fill out the next page and send it to the Seretariat at lamp2025@jlps.gr.jp
After receiving the application form, the invoice will be sent to you.

Due date for company movie, advertisements, and catalog: April 30, 2025.

Payment due date: June 30, 2025

Option: If you would like to join the banquet on DAY-3, June 12 in Toba Aquarium, please contact LAMP2025 Secretariat. (Banquet fee JPY 10000 will be charged separately via LAMP2025 online registration system.) <http://www.jlps.gr.jp/lamp/lamp2025/registration/>

To LAMP2025 SECRETARIAT

E-mail: lamp2025@jlps.gr.jp, FAX: +81-6-6879-8642

LAMP2025 SPONSORSHIP APPLICATION FORM

DATE		For Secretariat use		
COMPANY NAME				
DEPARTMENT				
APPLICANT'S INFORMATION	FULL NAME:			
	E-MAIL:			
BILLING ADDRESS				
SPONSORSHIP	CATEGORIES	FEE (JPY) 10% TAX Included	QUANTITY	SUB-TOTAL
	GOLD	200000		
	SILVER	100000		
	BRONZE	50000		
	CATALOG DISPLAY	30000		
	For WIRE-TRANSFER: Additional Bank Handling Charge JPY 4000 should be added.			
TOTAL AMOUNT				
URL FOR LINK				
<input type="checkbox"/> PAYMENT BY CREDIT CARD	Checkmark: <input type="checkbox"/> VISA <input type="checkbox"/> MASTER CARD <u>CARD NUMBER:</u> <u>CARD HOLDER'S NAME:</u> <u>EXPIRATION DATE (MONTH/YEAR):</u> / /			
<input type="checkbox"/> PAYMENT BY WIRE-TRANSE	Bank name (Bank code#) Sumitomo Mitsui Banking Corporation (#0009) Branch (Branch code#) Minami Senri (#189) SWIFT Code: S M B C J P J T Account name: Itpan Shadan Hojin Laser Kako Gatkai Account type: Regular (Futsu) Account Number: 1159822 Bank address: 1-2-D9-101, Tsukumodai, Suita, Osaka 565-0862, Japan Bank phone #: +81-6-6833-1911 Note: 1) Please make sure to add ¥4000 bank handling charge. 2) Please bear your local bank's handling charge by yourself.			

Personal information will be used only for administrative procedures and will not be used elsewhere.